

Substitute Form PTO-1448 (Modified)	U.S. Department of Commerce Patent and Trademark Office	Attorney's Docket No. 10559-586003	Application No. 10/802,991
<b>Information Disclosure Statement by Applicant</b> (Use several sheets if necessary)		Applicant Lawrence D. Wong	
		Filing Date March 16, 2004	Group Art Unit 1792
(37 CFR §1.98(b))			

## U.S. Patent Documents

Examiner Initial	Desig. ID	Document Number	Publication Date	Patentee	Class	Subclass	Filing Date If Appropriate
	AA						
	AB						
	AC						

## Foreign Patent Documents or Published Foreign Patent Applications

Examiner Initial	Desig. ID	Document Number	Publication Date	Country or Patent Office	Class	Subclass	Translation	
							Yes	No
	AD							
	AE							
	AF							

## Other Documents (include Author, Title, Date, and Place of Publication)

Examiner Initial	Desig. ID	Document
	AG	Baklanov, M.R., et al., "Comparative study of Porous SOG Films with Different Non-Destructive Instrumentation", <i>Proceedings of the IEEE 2001 International Interconnect Technology Conference</i> , pp. 189-191, June 2001.
	AH	Drage, J.S., et al., "Effects of Electron Beam Exposure on Poly(arylene Ether) Dielectric Films", <i>Mat. Res. Soc. Symp. Proc.: Low-Dielectric Constant Materials III</i> , vol. 476, pp. 121-128, April 1997.
	AI	Feiler, D., et al., "E-Beam Curing Process of Low-k Dielectrics for Unlabeled Vias in 0.25 $\mu$ m CMOS Technology", <i>Proc. 5<sup>th</sup> International Dielectrics for ULSI Multilevel Interconnection Conference (DUMIC)</i> , Catalog No. 99IMIC-44D, pp. 289-294, February 1999.
	AJ	Kawamura, S., et al., "New Measurement Technique of Pore Size Distribution of Porous Low-k Film", <i>Proceedings of the IEEE 2001 International Interconnect Technology Conference</i> , pp. 195-197, June 2001.
	AK	Lee, H.-J., et al., "Characterization of Porous Low-k Dielectric Thin Films Using X-Ray Reflectivity, Small Angle Neutron Scattering and Ion Scattering", <i>Proceedings of the IEEE 2001 International Interconnect Technology Conference</i> , pp. 247-249, June 2001.
	AL	Lee, H.-J., et al., "A Novel and Low Thermal Budget Planarization Scheme for Pre-Metal Dielectric Using Electron-Beam Cured HSQ (Hydrogen Silsesquioxane) in STC (Stacked Capacitor) DRAM", <i>Extended Abstracts of the 1999 International Conference on Solid State Devices and Materials</i> , pp. 502-503, September 1999.
	AM	Licata, T.J., et al., "Interconnect Fabrication Processes and the Development of Low-Cost Wiring for CMOS Products", <i>IBM Journal of Research and Development</i> , 39(4):419-435, July 1995.
	AN	Matsuki, N., et al., "Aurora Low-k PECVD Deposited SiOC Films for Copper Dual Damascene Interconnect Applications", ASM International, ASME Presentation November 2001, 24 pages.

Examiner Signature	Date Considered
EXAMINER: Initials citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.	